

Schottky Barrier Rectifier, Trench-based

NRTS1060PFS, NRVTS1060PFS

This TO-277 trench Schottky rectifier provides fast switching performance in a compact thermally efficient package. The TO-277 package provides an excellent alternative to the DPAK, offering thermal performance nearly as good in a package occupying less than half the board space. Its low profile makes it a good option for flat panel display and other applications with limited vertical clearance. The device offers low leakage over temperature making it a good match for applications requiring low quiescent current.

Features

- Package Provides Capability of Inspection and Probe After Board Mounting
- Low Forward Voltage Drop
- 175 °C Operating Junction Temperature
- NRV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

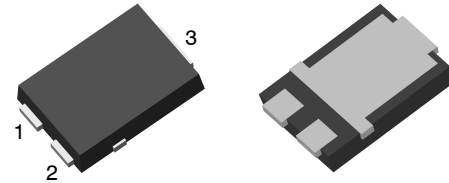
Mechanical Characteristics:

- Case: Epoxy, Molded
- Epoxy Meets Flammability Rating UL 94-0 @ 0.125 in.
- Lead Finish: 100% Matte Sn (Tin)
- Lead and Mounting Surface Temperature for Soldering Purposes: 260 °C Max. for 10 Seconds
- Device Meets MSL 1 Requirements

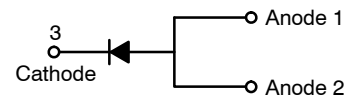
Applications

- Excellent Alternative to DPAK in Space-Constrained Automotive Applications
- Low Leakage for Higher Temperature Operation
- Output Rectification in Compact Portable Consumer Applications
- Freewheeling Diode used with Inductive Loads

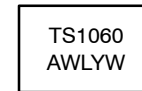
SCHOTTKY BARRIER RECTIFIER, 10 AMPERES 60 VOLTS



TO-277-3LD
CASE 340CZ



MARKING DIAGRAM



TS1060 = Specific Device Code
 A = Assembly Location
 Y = Year
 W = Work Week
 WL = Wafer Lot

ORDERING INFORMATION

| Device | Package | Shipping† |
|-----------------|---------------------|------------------------|
| NRTS1060PFST3G | TO-277 (Pb-Free) | 1,500 / Tape & Reel |
| NRVTS1060PFST3G | TO-277 (Pb-Free) | 1,500 / Tape & Reel |

† For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, [BRD8011/D](#).

NRTS1060PFS, NRVTS1060PFS

MAXIMUM RATINGS

| Symbol | Rating | Value | Unit |
|---------------------------------|---|-------------|------------------|
| V_{RRM} V_{RWM} V_R | Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage | 60 | V |
| $I_{F(AV)}$ | Average Rectified Forward Current ($T_C = 163\text{ }^\circ\text{C}$) | 10 | A |
| I_{FRM} | Peak Repetitive Forward Current, ($T_C = 160\text{ }^\circ\text{C}$, Square Wave, Duty = 0.5) | 20 | A |
| I_{FSM} | Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz) | 150 | A |
| T_{stg} | Storage Temperature Range | -65 to +175 | $^\circ\text{C}$ |
| T_J | Operating Junction Temperature | -55 to +175 | $^\circ\text{C}$ |
| | ESD Rating (Human Body Model) | 3B | |
| | ESD Rating (Machine Model) | M4 | |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

| Symbol | Characteristic | Max | Unit |
|------------------|--|-----|--------------------|
| $R_{\theta JA}$ | Thermal Resistance, Junction-to-Ambient (Assumes 600 mm ² , 1 oz. copper bond pad on a FR4 board) | 69 | $^\circ\text{C/W}$ |
| $R_{\theta JCT}$ | Thermal Resistance, Junction-to-Case, Top (Assumes 600 mm ² , 1 oz. copper bond pad on a FR4 board) | 61 | $^\circ\text{C/W}$ |
| $R_{\theta JCB}$ | Thermal Resistance, Junction-to-Case, Bottom (Assumes 600 mm ² , 1 oz. copper bond pad on a FR4 board) | 2.0 | $^\circ\text{C/W}$ |

ELECTRICAL CHARACTERISTICS

| Symbol | Characteristic | Typ | Max | Unit |
|--------|--|------------------------------|------------------------|---------------------|
| v_F | Instantaneous Forward Voltage (Note 1) ($i_F = 5\text{ A}$, $T_J = 25\text{ }^\circ\text{C}$) ($i_F = 5\text{ A}$, $T_J = 125\text{ }^\circ\text{C}$) ($i_F = 10\text{ A}$, $T_J = 25\text{ }^\circ\text{C}$) ($i_F = 10\text{ A}$, $T_J = 125\text{ }^\circ\text{C}$) | 0.49 0.42 0.57 0.53 | - - 0.66 0.65 | V |
| i_R | Instantaneous Reverse Current (Note 1) (Rated dc Voltage, $T_J = 25\text{ }^\circ\text{C}$) (Rated dc Voltage, $T_J = 125\text{ }^\circ\text{C}$) | 7 4.2 | 350 50 | μA mA |
| C_J | Junction Capacitance ($V_R = 1\text{ V}$, $T_J = 25\text{ }^\circ\text{C}$, 1 MHz) | 1023 | - | pF |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

1. Pulse Test: Pulse Width = 300 μs , Duty Cycle $\leq 2.0\%$.

TYPICAL CHARACTERISTICS

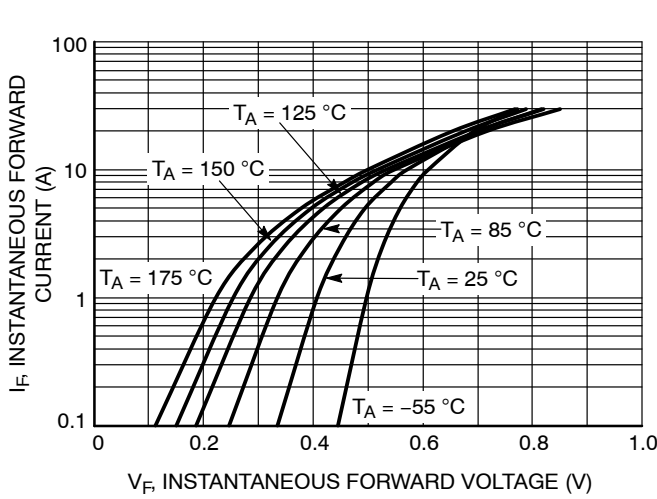


Figure 1. Typical Instantaneous Forward Characteristics

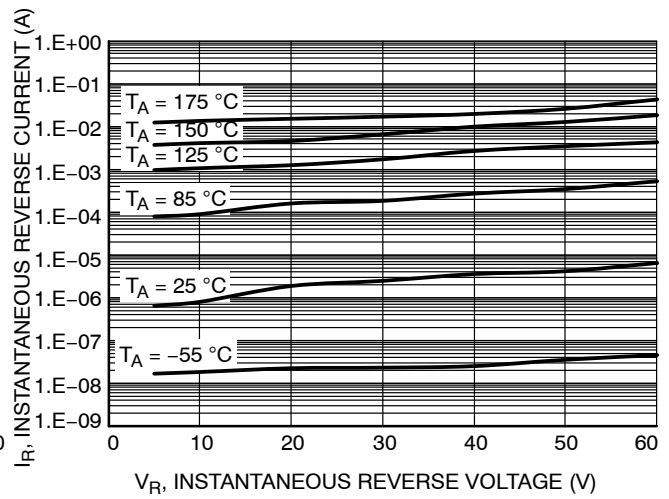


Figure 2. Typical Reverse Characteristics

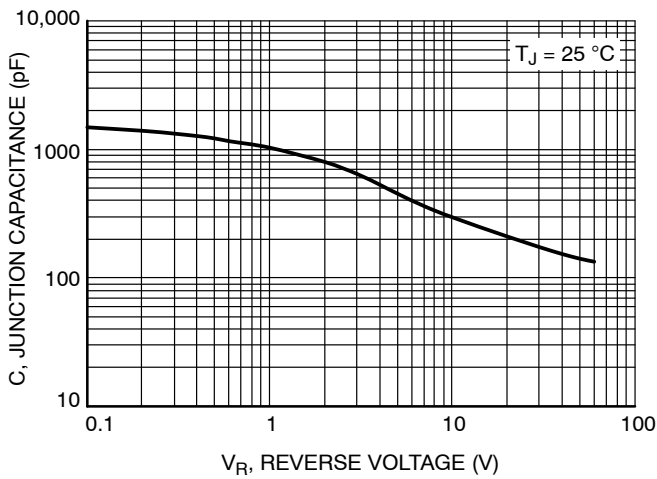


Figure 3. Typical Junction Capacitance

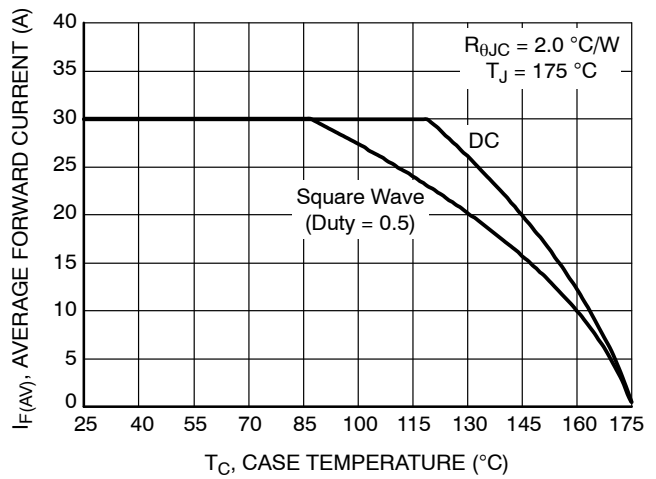


Figure 4. Current Derating

NRTS1060PFS, NRVTS1060PFS

TYPICAL CHARACTERISTICS (continued)

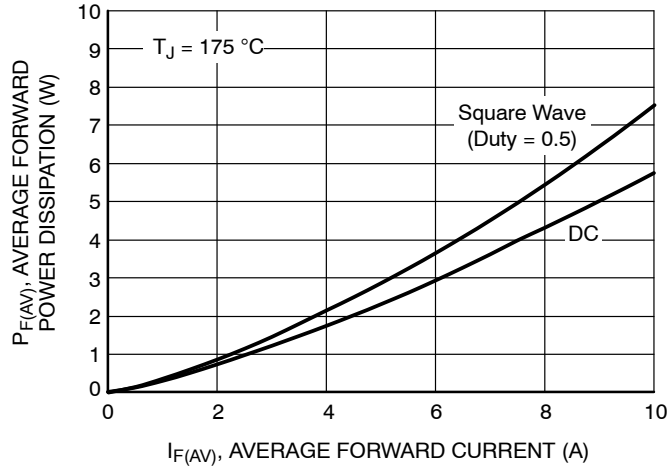


Figure 5. Forward Power Dissipation

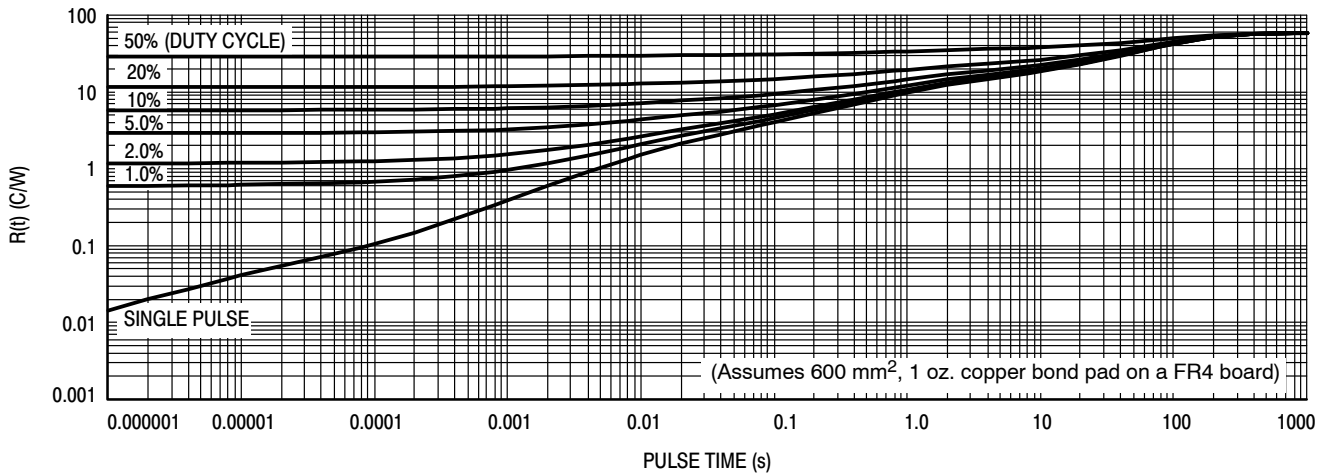


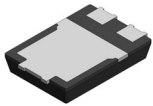
Figure 6. Typical Thermal Characteristics, Junction-to-Ambient

NRTS1060PFS, NRVTS1060PFS

REVISION HISTORY

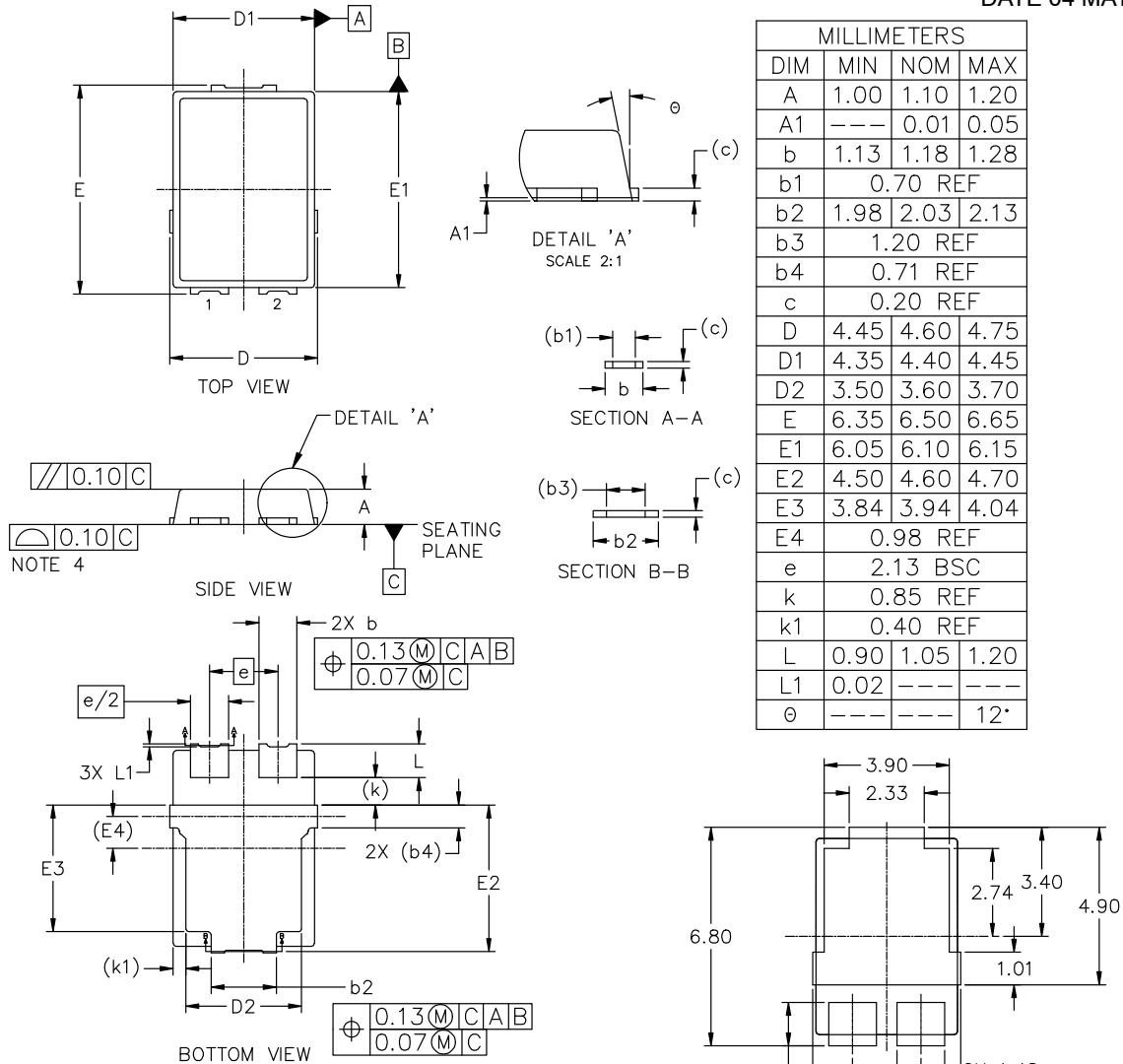
| Revision | Description of Changes | Date |
|----------|---|----------|
| 1 | Rebranded the Data Sheet to onsemi format. | 7/9/2025 |

This document has undergone updates prior to the inclusion of this revision history table. The changes tracked here only reflect updates made on the noted approval dates.



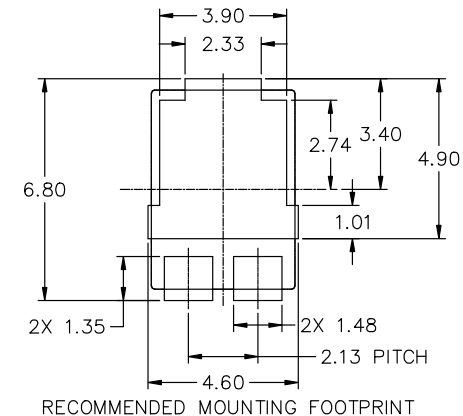
TO-277-3 4.40x6.10x1.10, 2.13P
CASE 340CZ
ISSUE B

DATE 04 MAY 2026



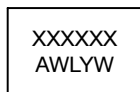
| MILLIMETERS | | | |
|-------------|----------|------|------|
| DIM | MIN | NOM | MAX |
| A | 1.00 | 1.10 | 1.20 |
| A1 | --- | 0.01 | 0.05 |
| b | 1.13 | 1.18 | 1.28 |
| b1 | 0.70 REF | | |
| b2 | 1.98 | 2.03 | 2.13 |
| b3 | 1.20 REF | | |
| b4 | 0.71 REF | | |
| c | 0.20 REF | | |
| D | 4.45 | 4.60 | 4.75 |
| D1 | 4.35 | 4.40 | 4.45 |
| D2 | 3.50 | 3.60 | 3.70 |
| E | 6.35 | 6.50 | 6.65 |
| E1 | 6.05 | 6.10 | 6.15 |
| E2 | 4.50 | 4.60 | 4.70 |
| E3 | 3.84 | 3.94 | 4.04 |
| E4 | 0.98 REF | | |
| e | 2.13 BSC | | |
| k | 0.85 REF | | |
| k1 | 0.40 REF | | |
| L | 0.90 | 1.05 | 1.20 |
| L1 | 0.02 | --- | --- |
| theta | --- | --- | 12° |

- NOTES:
1. DIMENSIONING AND TOLERANCING AS PER ASME Y14.5M, 2018.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. DIMENSION b, b1, b2, b3, b4 and c TO BE MEASURED ON FLAT SECTION OF THE LEAD, BETWEEN 0.13 AND 0.25mm FROM LEAD TIP.
 4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
 5. POSITIONAL TOLERANCE APPLIES TO THE TERMINALS AND EXPOSED PAD.
 6. A1 IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
 7. DIMENSION D1 AND E1 TO BE DETERMINED AT DATUM PLANE C.



RECOMMENDED MOUNTING FOOTPRINT
*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERM/D.

GENERIC MARKING DIAGRAM*



- XXXXXX = Specific Device Code
A = Assembly Location
Y = Year
W = Work Week
WL = Wafer Lot

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

| | | |
|------------------|--------------------------------|--|
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| DESCRIPTION: | TO-277-3 4.40x6.10x1.10, 2.13P | PAGE 1 OF 1 |

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